

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent No.: 7,196,417 B2

Applicant(s): Tomohei SUGIYAMA et al.

Issued: March 27, 2007

Customer No.: 85775

For: METHOD OF MANUFACTURING A LOW EXPANSION MATERIAL AND
SEMICONDUCTOR DEVICE USING THE LOW EXPANSION MATERIAL

REQUEST FOR CERTIFICATE OF CORRECTION OF PATENT

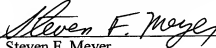
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Attached in duplicate is Form PTO-1050, with at least one copy being suitable for printing.

- ☐ The error was the fault of the Patent and Trademark Office, no fee is required.
- ☒ The error was not the fault of the Patent and Trademark Office, please charge the requisite fee of \$100 to Deposit Account No. 504827, Order No. 1004378.51180.
- ☒ The Commissioner is hereby authorized to charge any additional fees which may be required by this paper, or credit any overpayment to Deposit Account No. 504827, Order No. 1004378.51180.

Respectfully submitted,
Locke Lord Bissell & Liddell LLP


Steven F. Meyer
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Dated: September 10, 2009

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UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NUMBER : 7,196,417 B2
DATED : March 27, 2007
INVENTOR(S) : Tomohel SUGIYAMA et al.

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

IN THE SPECIFICATION

Column 1, line 28, please delete "in thermal" and insert therefore -- in the thermal --;

Column 1, line 29, please delete "Si or other" and insert therefore -- Si or any other --;

Column 1, line 30, please delete "5 and Al" and insert therefore -- 5, and Al --;

Column 2, line 60, please delete "unsintered Sic particles" and insert therefore -- unsintered SiC particles --;

Column 2, line 67, please delete "expan" and insert therefore -- expan- --;

Column 4, line 5, please delete "as low thermal" and insert therefore -- as low a thermal --;

Column 4, line 55, please delete "The mold/melt temperature is set to" and insert therefore -- The mold/melt temperature is set to 700/800°C for each of Samples S5 to S8. --;

Column 5, line 61, please delete "as heat spreader" and insert therefore -- as a heat spreader --; and

Column 6, line 7, please delete "as heat spreader" and insert therefore -- as a heat spreader --.

ADDRESS ASSOCIATED WITH CUSTOMER NUMBER: **85775**

PATENT NO. 7,196,417 B2
No. of additional copies



This collection of information is required by 37 CFR 1.322, 1.323, and 1.324. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 1.0 hour to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Attention Certificate of Corrections Branch, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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